



Material Composition Declaration

EPC2052

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2/18/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	4.2 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum (%)	Mass
			(mg)	(%)		(ppm)
Chip	Silicon	7440-21-3	3.5372	84.5055	86.7173	845055
	Silicon oxide	7631-86-9	0.0142	0.3395		3395
	Silicon nitride	12033-89-5	0.0065	0.1545		1545
	Gallium nitride	25617-97-4	0.0126	0.2999		2999
	Aluminum	7429-90-5	0.0262	0.6253		6253
	Aluminum nitride	24304-00-5	0.0029	0.0681		681
	Titanium	7440-32-6	0.0005	0.0121		121
	Titanium nitride	25583-20-4	0.0027	0.0641		641
	Copper	7440-50-8	0.0009	0.0208		208
	Tungsten	7440-33-7	0.0011	0.0256		256
	Polyimide		0.0252	0.6019	6019	
Under Bump Metal	Titanium	7440-32-6	0.0003	0.0077	0.2016	77
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0081	0.1939		1939
Solder Bump	Tin	7440-31-5	0.5229	12.4924	13.0811	124924
	Silver	7440-22-4	0.0219	0.5232		5232
	Copper	7440-50-8	0.0027	0.0654		654
Sum in total:			4.1857	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.